

# Organic PCB for Probe Card Application

Our state-of-the-art technology provides innovative organic PCBs, best suited for probe card applications demanding huge wiring capacity and high-quality signal integrity.

Our solutions for the most advanced semiconductor device testing are based on our technologies and know-how accumulated over half a century.

## Any layer IVH structure for huge wiring capacity and design flexibility

F-ALCS technology enabling over 35,000 wires representing twice the capacity of conventional PCBs.

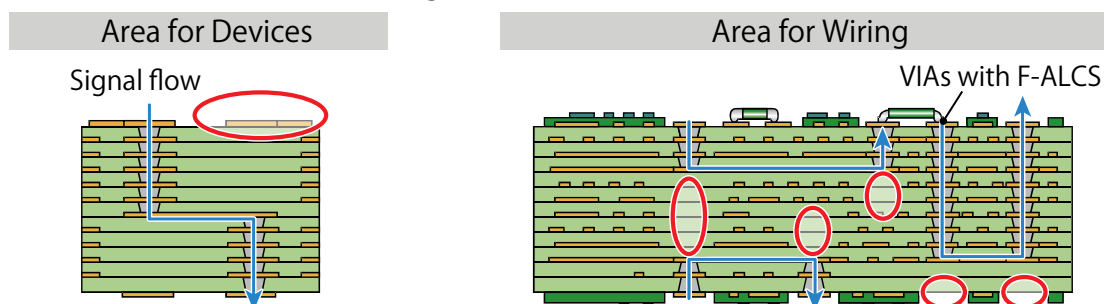
## One-time lamination process to shorten the fabrication lead time

Our innovative technology “F-ALCS” reduces the process steps by 50% and shortens the delivery time.

## Any layer stubless structure for low loss high speed signal transmission

Narrow pitch contacts and high frequency device testing (>5GHz) are enabled with this technology.

### Advantages with the F-ALCS structure



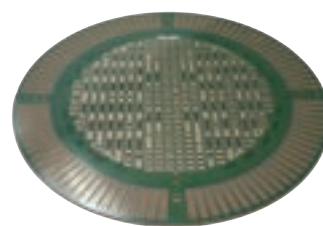
The F-ALCS structure dramatically expands the available space for device mounting and signal wiring.

### Products



Organic Probe Card for Logic LSI (Interposer Type)

Layer Construction	42 Layers (7+28(F-ALCS)+7)
PCB Size, Thickness	100mm x 100mm, 2.7mm
# of Nets, Pad Pitch, R(Signal)	500nets/DUT, 125 $\mu$ m, R<2 $\Omega$



Organic Probe Card for DRAM Memory

Layer Construction	74 Layers (F-ALCS)
PCB Size, Thickness	$\phi$ 520mm, 7.4mm
# of Nets (Signal)	30,000wires

